

**IMPRS Lectures on
SPACE INSTRUMENTATION**

25-29 October 2010

MPS , Katlenburg-Lindau :

Space Instrument Development

(based on lecture by Hermann Hartwig, Dec. 2006)

Reinhard Meller, MPS

After winning the proposal selection

it usually takes **about 8 years** for a major instrument up to launch .

Examples :

SOHO (ESA solar cornerstone mission)

instrument selection : 1988 ⇒ launch : Dec 1995

ROSETTA (ESA planetary cornerstone mission)

instrument selection : 1995 ⇒ launch : Mar 2004

W H Y ?

Commercial off-the-shelf (COTS) instruments usually **will not work** for space because they

- are too heavy
- will not survive the launch loads
- will stop functioning under space conditions:

space is a very hostile environment !

A closer look at :

➤ **mass** : why it is important

SOHO : scientific instruments accumulated = 610 kg
spacecraft mass at launch = 1850 kg
launcher mass = 237 500 kg
launch cost ATLAS II AS = 72 000 000 €
specific launch cost for instrument : **118 000 €/kg**

ROSETTA: scientific instruments accumulated = 186 kg
spacecraft mass at launch = 2900 kg
launcher mass = 760 000 kg
launch cost ARIANE 5 = 100 000 000 €
specific launch cost for instrument : **537 634 €/kg**

[for comparison : price of gold (Au) : **17 500 €/kg]**

A closer look at :

➤ **total launch support mass / scientific payload mass ratio:**

SOHO : $(237\,500 + 1850 - 610) \text{ kg} / 610 \text{ kg} = 391$

ROSETTA: $(760\,000 + 2900 - 186) \text{ kg} / 186 \text{ kg} = 4101$

ratio depends on space mission trajectory

=> Scientific instrument mass saving is an important issue!

A closer look at :

➤ **launch loads** : why they are important

for smaller instruments the Design Loads can be as high as **60 x gravity** (60g)

for larger instruments (> 50 kg) still **25 x gravity**

=> Design must have : low mass ; high strength !

➤ **hostile space environment**

- high vacuum
- zero-g
- radiation (electromagnetic & energetic particles)
- very low temperatures to dark space background
- extremely high thermal loads on sun illuminated side (e.g. Solar Orbiter)

examples for unusual effects, occurring in space environment :

- high vacuum cleans metallic surfaces ⇒ **cold welding of moving part**
design shall avoid metal-to-metal contacts !
- usual liquid lubricants evaporate in vacuum ⇒ **bearings seize**
use vacuum-compatible dry lubrication films !
- energetic particles passing through semiconductor devices create charge clouds ⇒ **bit flips in memory cells (SEU single event upsets)**
implement hardware error correction function into design !
or –worse- create conductive channels in insulating layers between power conductors ⇒ **self-sustaining short circuit (latch-up effect)**
implement latch-up protection circuits into design !
- high vacuum : no convective cooling for electronics ⇒ **electronics overheat**
- zero gravity : gravity assisted heatpipes don't work ⇒ “
careful design of conductive/radiative heat transfer !
- high vacuum : outgassing of organic materials; EUV “cracking“ of molecular deposits on cold surfaces (detectors, optics) ⇒ **carbon black blinding**
careful material selection ; cleanliness control program !

For all these reasons

- **space instruments are custom-designed one-of-a-kind items**
- **building these unique instruments follows a universal pattern :**
 - **staged development with milestone peer reviews**
 - **succession of models with increasing complexity and level of detail**

Instrument Development Cycle : overview

➤ Preliminary Design (Phase A), ends with:

Preliminary Design Review (**PDR**)

hardware delivery : **STM** Structural / Thermal Model

➤ Detailed Design (Phase B) , ends with:

Critical Design Review (**CDR**)

hardware delivery : **EM** Electrical or Engineering Model

➤ Flight Hardware Manufacturing (Phase C)

➤ Assembly/Integration/Verification - AIV (Phase D) ,

optional with mid-term Test Readiness Review (**TRR**); ends with :

Flight Acceptance or Pre-Shipment Review (**FAR / PSR**)

hardware delivery : **FM** Flight Model(s) + **FS** Flight Spare Model

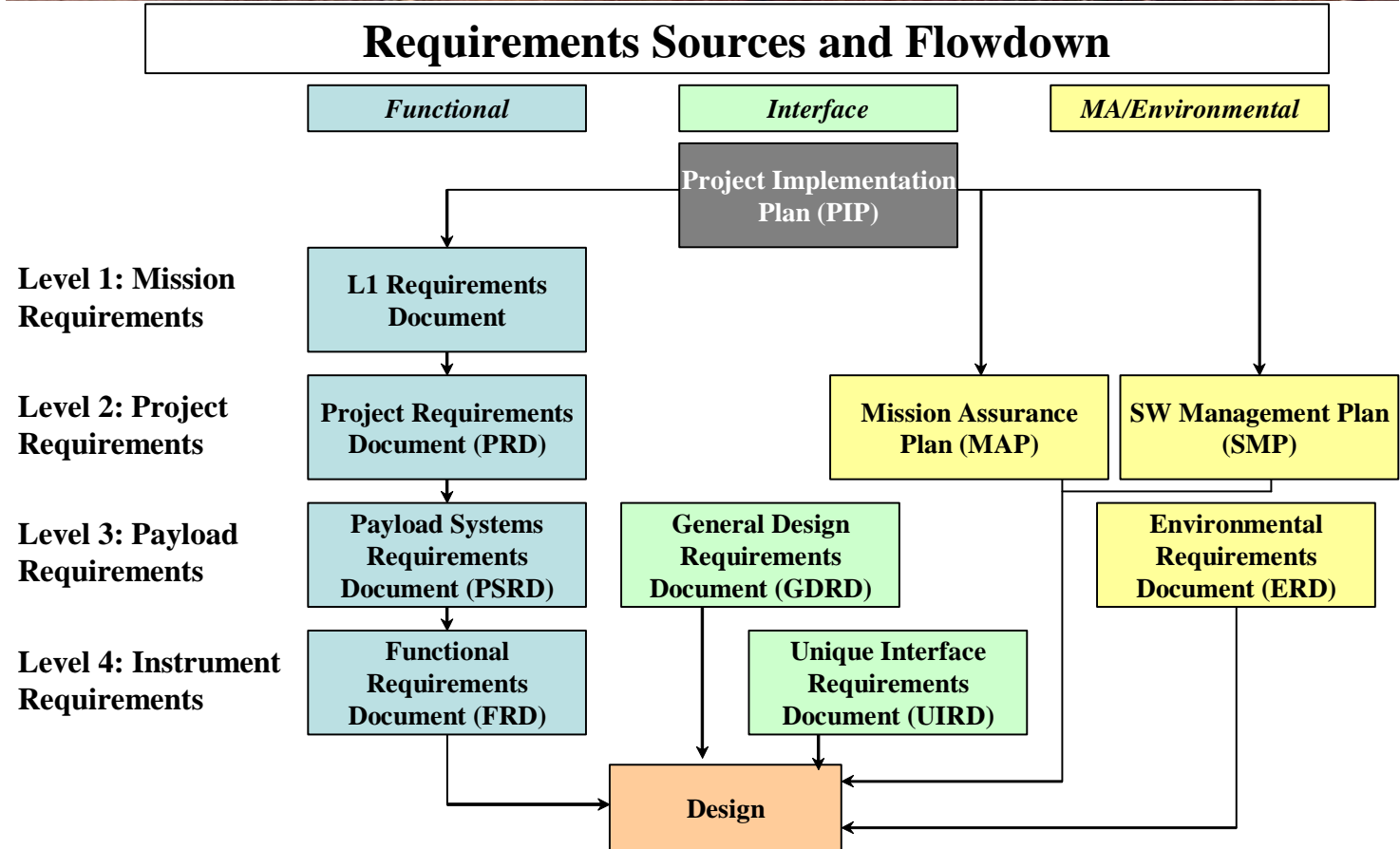
A : Preliminary Design Phase :

- **establish requirement flowdown** : from mission requirements to payload requirements to instrument functional requirements to instrument specification
- **allocate mass and power budgets** to subsystems
- **define mechanical and electrical interfaces** between subsystems
(e.g. form factors for PCBs, connector types and arrangement etc)
- **determine dimensions, volumes, shapes**
- **write specifications** for subsystems, that will be subcontracted to industry
- **assemble STM** (form, fit, no functions) = mass and thermal “dummy“

- ⇒ **Preliminary Design Review** ; **STM delivery**

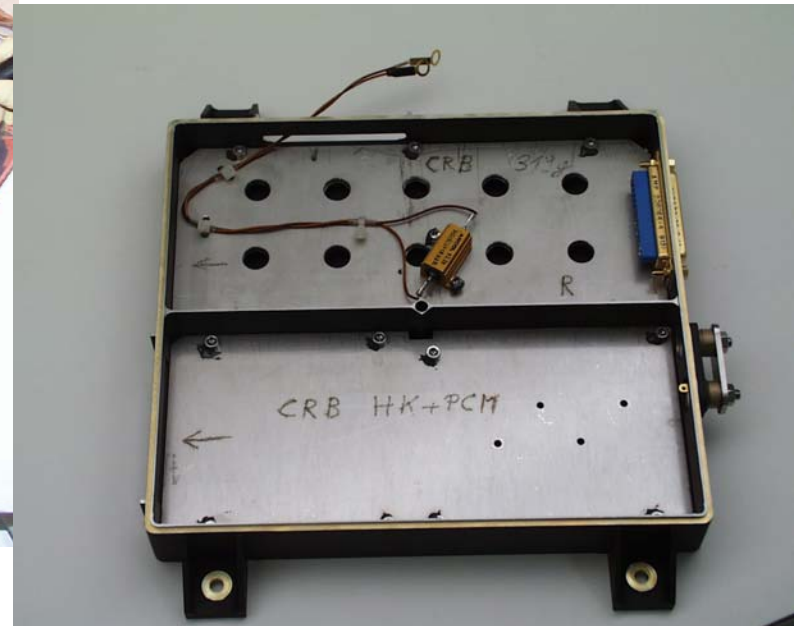
example:

requirement
flowdown
diagram
for DAWN
Framing Camera



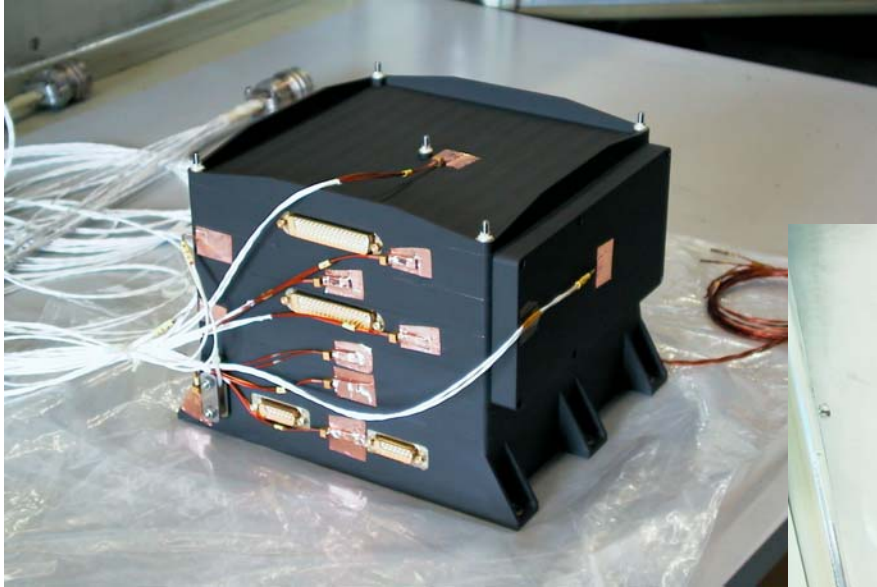
A : ROSETTA / OSIRIS STM examples:

➤ Electronics Unit & CRB Unit assembly



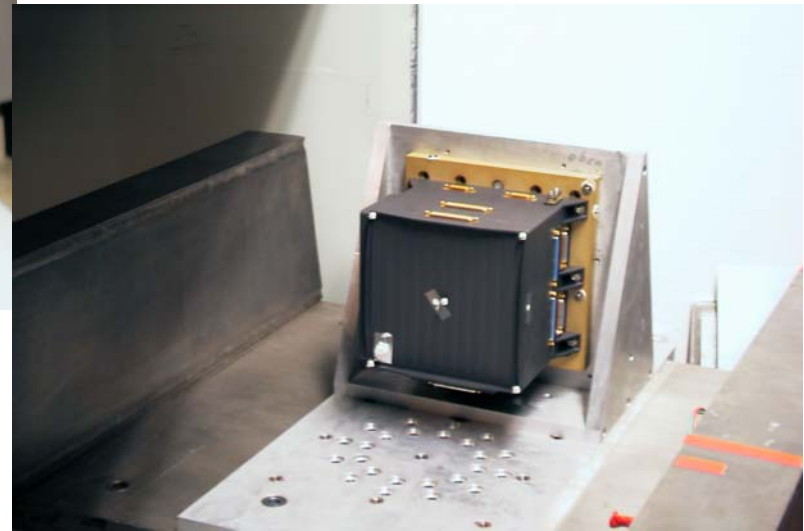
cont. A : ROSETTA / OSIRIS STM examples:

- Electronics Unit prepared for thermal balance test



cont. A : ROSETTA / OSIRIS STM examples:

➤ Electronics Unit sine vibration and static load test



cont. A : ROSETTA / OSIRIS STM examples:

➤ NAC & WAC STM delivery preparation



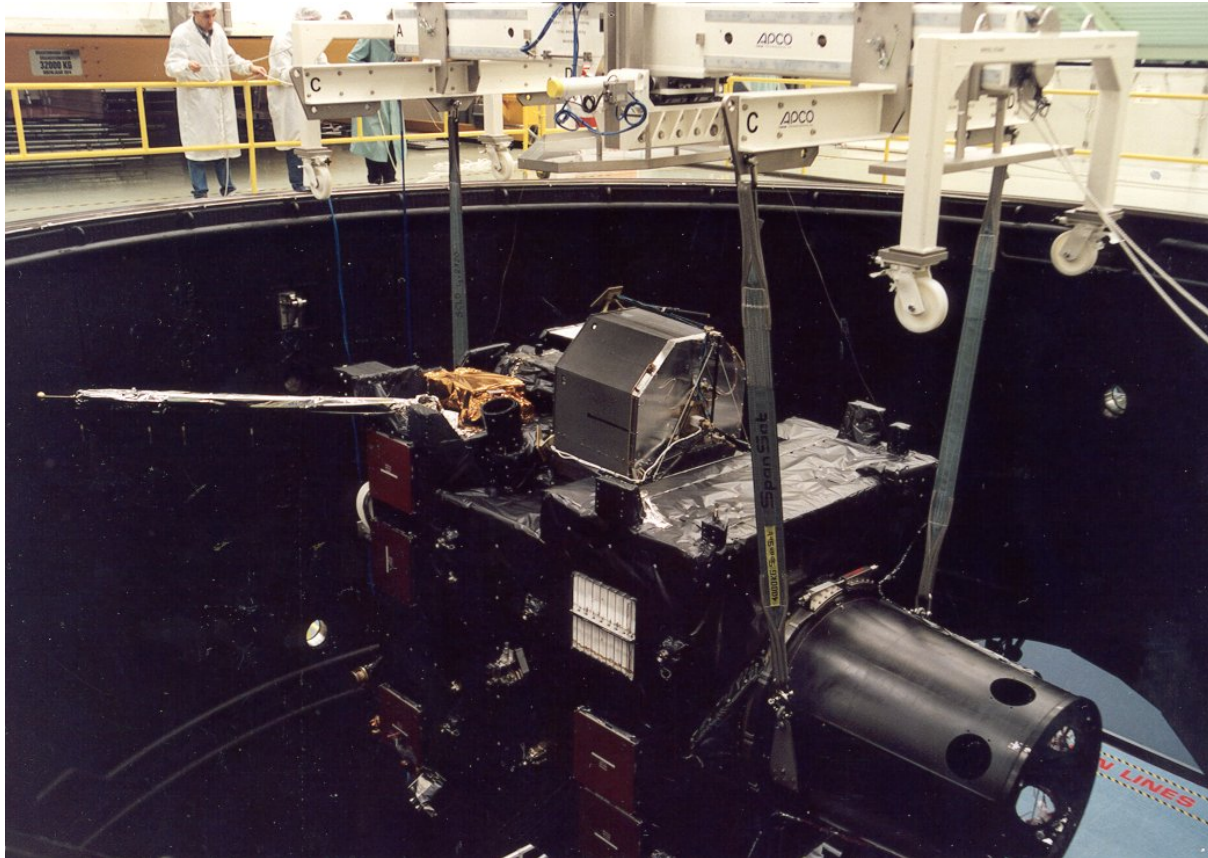
cont. A : ROSETTA / OSIRIS STM examples:

- NAC STM delivery to ESA and integration onto ROSETTA STM S/C



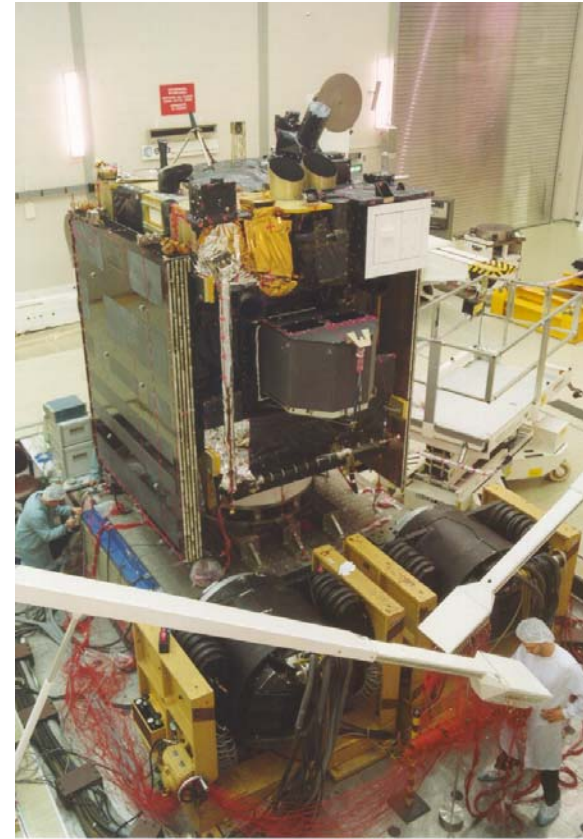
cont. A : ROSETTA / OSIRIS STM examples:

- OSIRIS STM integrated on ROSETTA for thermal verification test



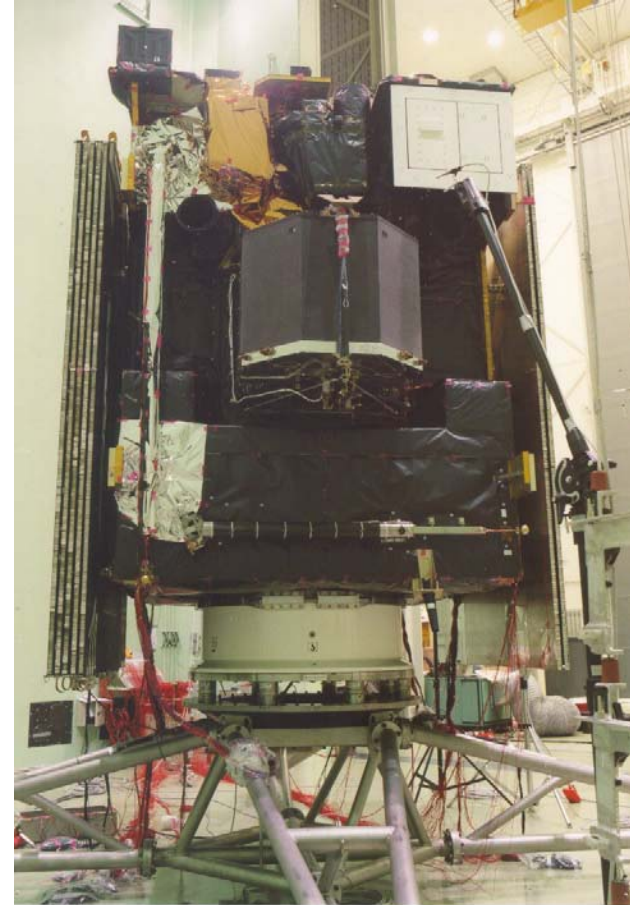
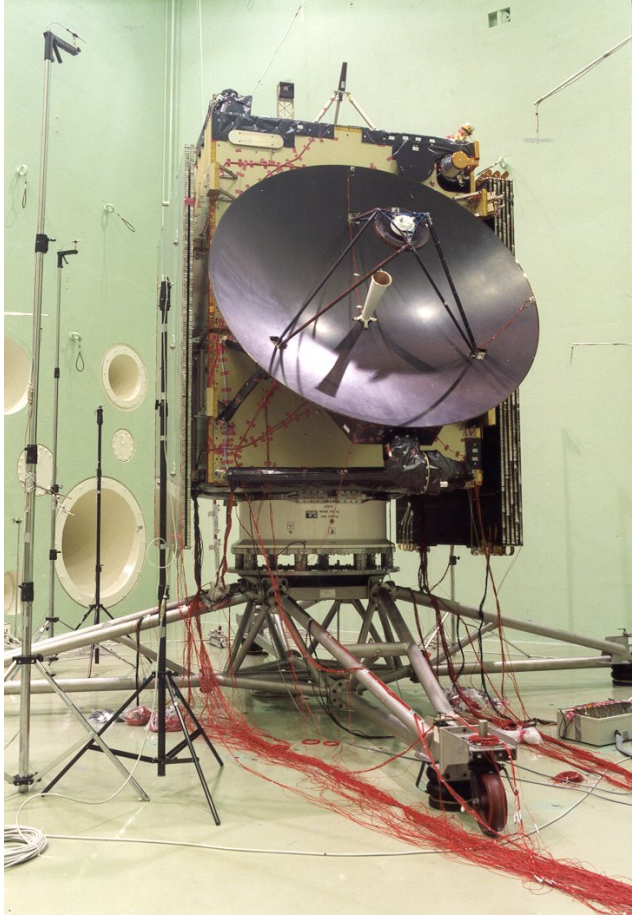
cont. A : ROSETTA / OSIRIS STM examples:

- ROSETTA STM S/C incl. STM payload instr. prepared for vibration testing



cont. A : ROSETTA / OSIRIS STM examples:

- ROSETTA STM incl. STM payload instruments acoustic noise test setup



B : Detailed Design Phase :

- define / select materials and processes
 - design parts , select components
 - write basic operational code / software
 - generate mathematical models for:
 - structural analysis (Finite Element Model)
 - thermal analysis
 - validate models and pass on to S/C contractor (to be included into their global model)
 - perform Failure Modes, Effects and Criticality Analysis (FMECA)
 - assemble EM (form & fit as good as possible, all functions; components not space rated); verify
 - functionality and interfaces (power / command & telemetry)
 - ⇒ **Critical Design Review** ; **EM delivery**
-

Example :

Design reviews :

Agenda for the Critical Design Review

Framing Camera DAWN mission

DAWN Framing Camera (FC) Critical Design Review - CDR May 18 & 19, 2004

MPAe, Katlenburg-Lindau, Germany

Tuesday May 18, 2004

- 09:00 Welcome and Introduction – H. U. Keller
- 09:10 Goal of the Meeting – D. Norris
- 09:20 DAWN Project Status – C. Russell
- 09:30 Overview FC – Science Objectives and Requirements - H. U. Keller
- 09:50 FC Team Organigram and Top Level Workpackages – H. Sierks
- 10:00 Instrument Concept and Implementation – H. Hartwig
- 10:15 **Coffee Break**
- Camera Head**
- 10:30 Optical Design – H. Mosebach/K-T
- 10:45 Lens System, Filters, Baffle and related Analysis – H. Mosebach/K-T
- 11:00 CCD and Front End Electronics – S. Mottola
- 11:20 Front Door Mechanism and Fail Safe Mechanism - H. Hartwig
- 11:30 Filter Wheel Mechanism – H. Hartwig
- 11:45 Discussion
- 12:00 **Lunch Break**
- Electronics Box**
- 13:00 Electrical Interfaces Block Diagram & Grounding Concept – I. Hejja
- 13:10 Data Processing Unit and Mass Memory – H. Michalik/IDA
- 13:30 Power Converter Unit – R. Enge
- 13:45 Mechanism Controller Unit – W. Kuehne
- 14:00 Housekeeping Data Acquisition – I. Hejja
- 14:15 FC Heater Concept - H. Sierks
- Resources**
- 14:30 Power Breakdown – H. Sierks
- 14:40 Mass Breakdown – H. Hartwig
- 14:50 MICD & Accommodation – H. Hartwig
- 15:00 **Coffee Break**
- Instrument Modelling**
- 15:15 Structural Design – H. Hartwig
- 15:30 Thermal Design – H. Hartwig with H. P. Schmidt/DLR
- Software**
- 16:00 Low Level Software - H. Michalik/IDA
- 16:10 Operation Software – H. Michalik/IDA
- 16:30 EGSE Configuration and Software – H. Michalik/IDA
- 16:45 EM demonstration run in room S1-49

Wednesday May 19, 2004

- 09:00 Model Philosophy and Schedule – H. Sierks
- 09:20 Qualification Approach and Environmental Test Matrix – H. Sierks
- 09:30 QA Approach and Status – M. Richards
- 09:45 Operations Plans – P. Gutierrez
- 10:00 Calibration Plans – K. Schneider
- 10:15 **Coffee Break**
- 10:30 FC Data Processing Approach – R. Jaumann
- 10:50 Risk Mitigation Plan – H. Sierks
- 11:00 Review of PDR RFAs – H. Sierks
- 11:30 Discussion
- 12:00 **Lunch Break**
- 13:30 Board Summary, Action Items, and Wrap-up
- 17:00 Adjourn

Splinter Meetings as required.

Board Members:

Dave Norris (Chairman)
Fred Vescehus
John Schlu
F. Gliem
K. Wilhelm

Attendees List:

UCLA
Chris Russell
Steve Joy

JPL
Ed Miller
Betina Pavri
Khanara Ellers
Paul Hesse
Carol Polanskey
Jerry Dalton

Orbital
Mike Violet

MPAe

Example :

**structural
mathematical
model**

**Finite Element
Analysis**

**Framing Camera
on the DAWN
mission**

DAWN

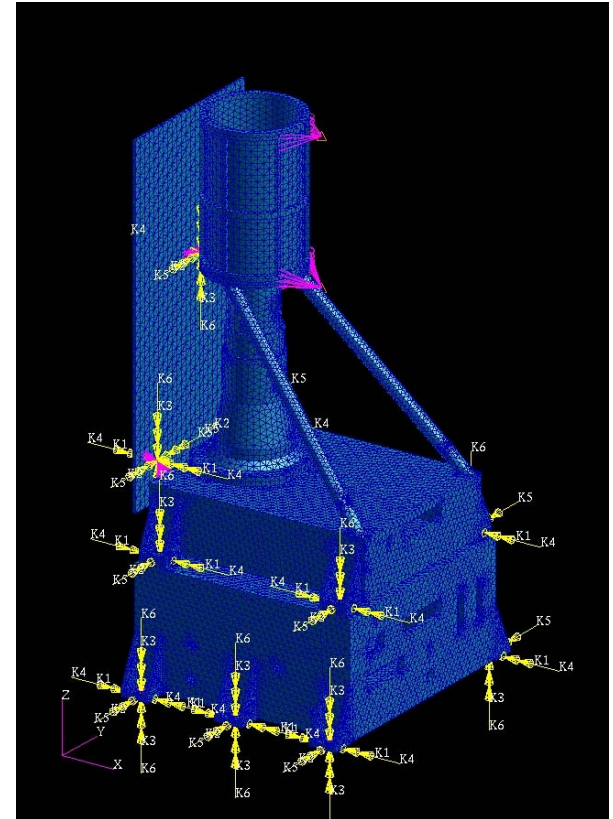
A Journey to the Beginning of the Solar System

Structural Analysis



Finite Element Analysis : Modelling

- model analyzed with :
MSC NASTRAN
- pre-/post-processing with :
MSC PATRAN
- element type used :
TET10(3D)
- element size :
4mm global edge length,
smaller in critical areas
- model size :
153 715 elements
288 605 nodes
78 spring elements
22 multi-point constraints



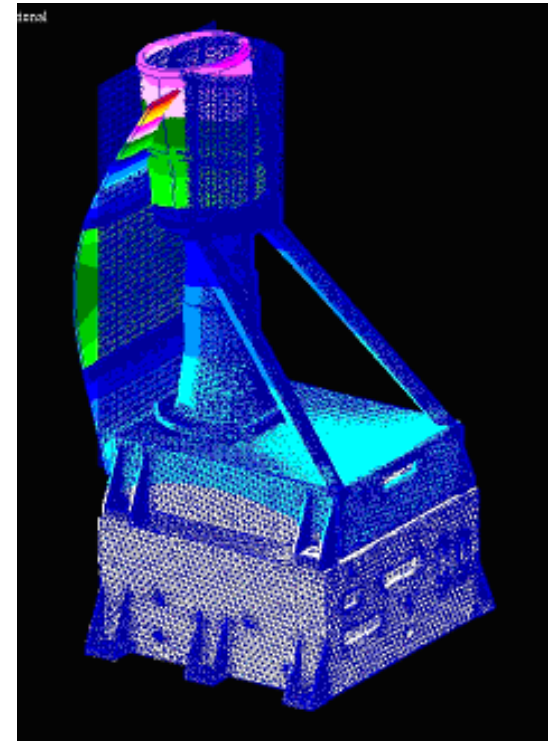


Example:

Finite Element Analysis cont'd:

Finite Element Analysis : Dynamics : 3rd Eigenmode

| Mode Nr. | Frequency in [Hz] | Remarks |
|----------|-------------------|---|
| 1 | 353.48 | bending of mainly the radiator but also the baffle around y-axis |
| 2 | 377.18 | swinging of tubus/baffle in y-direction (and bending around x-axis) |
| 3 | 414.42 | swinging of tubus/baffle in x-direction (and bending around y-axis) |
| 4 | 447.40 | bending of the radiator around z-axis |
| 5 | 670.00 | longitudinal vibration of the structure in z-direction |
| 6 | 737.16 | bending of the baffle around y-axis |
| 7 | 813.82 | local vibrations |
| 8 | 937.80 | 2 nd mode for swinging of tubus/baffle in y-direction |
| 9 | 990.14 | longitudinal vibrations in z-direction |
| 10 | 1049.16 | bending of radiator around y-axis |



Example :

thermal
mathematical
model

Finite Difference
Analysis

(ESATAN/ESARAD)

Framing Camera
on the DAWN
mission

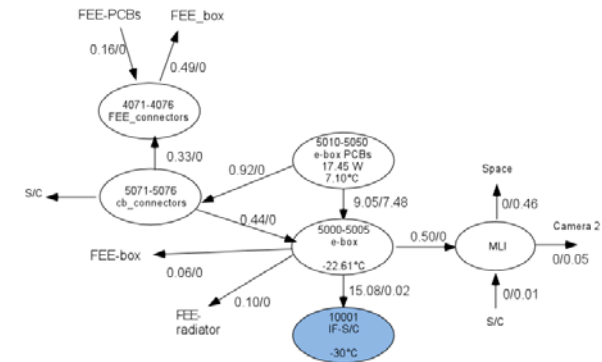
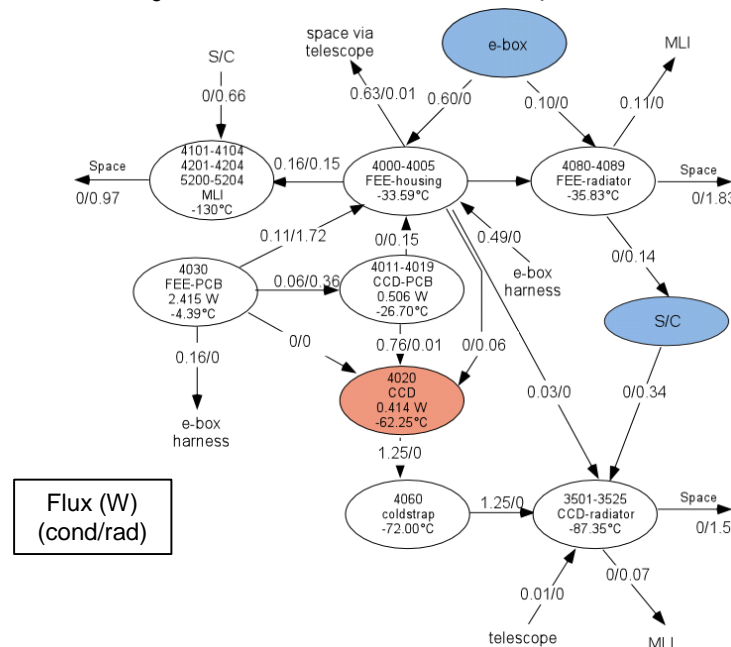


Dawn Framing Camera

Thermal Control Subsystem

Steady State Analysis - Operations (continued)

- Results : cold case heat fluxes from CCD and adjacent nodes to space



Example :

Delivery reviews :

Documentation to be ready before instrument H/W delivery

•Preliminary Design Review (STM)

•Critical Design Review (EM)

•Flight Acceptance Review (FM, FS)

OSIRIS Camera System on ROSETTA



OSIRIS

Reference: **RO-RIS-**
 Issue: Rev.:
 Date:
 Page:

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Figure 1: Sample figure (caption below figure, use "insert picture" to create figure.....)

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Table 1: Sample table (caption above table, use "insert caption - label table").....

C / D : Assembly / Integration / Verification :

- **Controlled and documented flight parts production & procurement; population of Printed Circuit Boards; in Clean Room ; ESD protected etc**
- **Testing at subsystem and system level:**
 - **Functional tests , including S/C interface verification (with S/C simulator)**
 - **Performance Tests / Calibration**
 - **Environmental tests :**
 - **Vibration**
 - **Pyro-Shock**
 - **Thermal-Vacuum / Thermal- Balance**
 - **Mechanism Lifetime**
 - **Electro-Magnetic Compatibility (EMC)**
 - **Physical properties**
 - **Interface Metrology**
 - **Mass**
 - **Center of Gravity**
 - **Moments of Inertia**

Example:

OSIRIS E-Box Module Test Philosophy and Test Matrix

| Test item | QM | STM | EEM | FM | FS | responsible |
|---|---------|-------|---------|---------------------|---------------------|-------------|
| Physical Properties (COG, Mass, Dimensions) | M / X | X | M / X | M / X | M / X | All / MPAE |
| Vibration | Q | Q | --- | A | A | All / MPAE |
| Shock | Q | (Q) | --- | --- | --- | All / MPAE |
| Acoustic Noise | tbd. | (X) | --- | --- | --- | All / MPAE |
| Thermal Balance | M / X | X | X | --- | --- | All / MPAE |
| Thermal Vacuum | Q | --- | --- | A | A | All / MPAE |
| Mechanical Functional | M / X | M / X | M / X | M / X | M / X | All / MPAE |
| Electrical Functional | M / X | --- | M / X | M / X | M / X | All / MPAE |
| Optical Functional | --- | --- | --- | --- | --- | --- |
| Electrical Test (Grounding, Bonding, Isolation) | M / X | --- | M / X | M / X | M / X | All / MPAE |
| EMC (Conducted and Radiated Interference) | (M) / X | --- | --- | X conducted only | X conducted only | All / MPAE |
| DC Magnetic Properties | (M) / X | --- | --- | X | X | All / MPAE |
| Alignment | --- | --- | --- | --- | --- | --- |
| Calibration | M / X | --- | (M)/(X) | M / X | M / X | All / MPAE |

Models:

| | | |
|-------|------------------------------|----------------------|
| QM : | Qualification Model | not delivered to ESA |
| STM : | Structural Thermal Model | } (build by MPAE) |
| EEM : | Electrical Engineering Model | |
| FM : | Flight Model | } to ESA |
| FS : | Flight Spare Model | |

Module Tests, to be performed at the responsible institutes or manufacturers prior E-Box integration:

| | |
|-------|----------------------------------|
| M : | Required, no specific test level |
| () : | Desirable |

Instrument Tests (Modules integrated in E-Box), to be done at MPAE or testhouse, supported by the responsible institutes:

| | |
|-------|------------------------|
| Q : | Qualification Level |
| A : | Acceptance Level |
| X : | no specific test level |
| () : | Desirable |
| --- | Not Required |

Vibration testing :

simulates launch loads (structural and acoustic)

power of ARIANE-5 at launch = 30 million h-p ; acoustic pressure level ~145 dB !

Test :

on electrodynamic shaker systems: giant “loudspeaker“ coil drive , w/o membrane

sine test : swept single frequency ; control = peak acceleration

random test: wide-band random “noise“ spectrum; control = power spectral density profile

SIR-2 Sine qualification levels (TBC by ISRO)
for O-Box ; on ASS panel extension

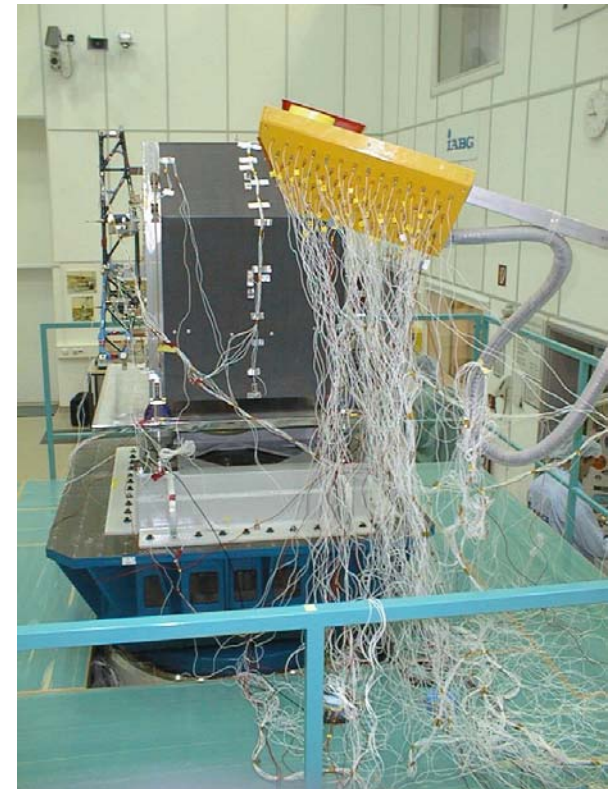
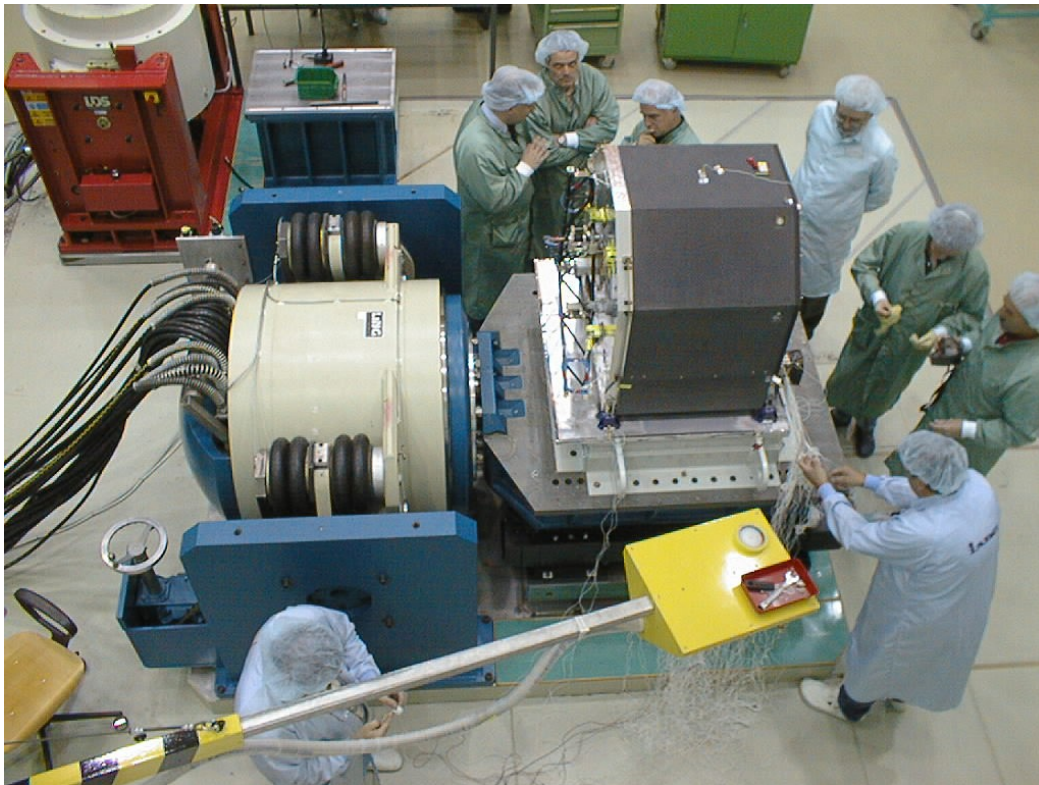
| frequency | in-plane (X and Y) | frequency | out-of-plane (Z) |
|-----------------|--------------------|-----------------|------------------|
| 5 Hz to 20 Hz | 9.3 mm(0-p) | 5 Hz to 18 Hz | 11.5 mm(0-p) |
| 20 Hz to 70 Hz | 15 g const. | 18 Hz to 50 Hz | 30 g const. |
| 70 Hz to 100 Hz | 8 g const. | 50 Hz to 70 Hz | 20 g const. |
| | | 70 Hz to 100 Hz | 15 g const. |
| sweep rate | 2 oct/min | | 2 oct/min |

SIR-2 Random qualification levels (TBC by ISRO)
for O-Box ; on ASS panel extension

| frequency | in-plane p.s.d. (X and Y axis) | out-of-plane p.s.d. (Z axis) |
|-------------------|----------------------------------|--------------------------------|
| 20 Hz to 100 Hz | + 3 dB/octave | + 3 dB/octave |
| 100 Hz to 700 Hz | 0.1 g ² /Hz | 0.3 g ² /Hz |
| 700 Hz to 2000 Hz | - 3 dB/octave | - 6 dB/octave |
| RMS level | 11.8 | 18.2 g |

Example : ROSETTA Lander STM on shaker at IABG, Munich

measurement accelerometer wiring



Thermal Vacuum / Thermal Balance Test :

tests thermal behaviour in special test chambers under space conditions

(high vacuum ; cold space ; solar illumination / planetary thermal emission)

passive protective systems:

- Multi-Layer Insulation (MLI) ;

- thermal radiators / absorbers

- second-surface mirrors (reject heat against solar irradiation)

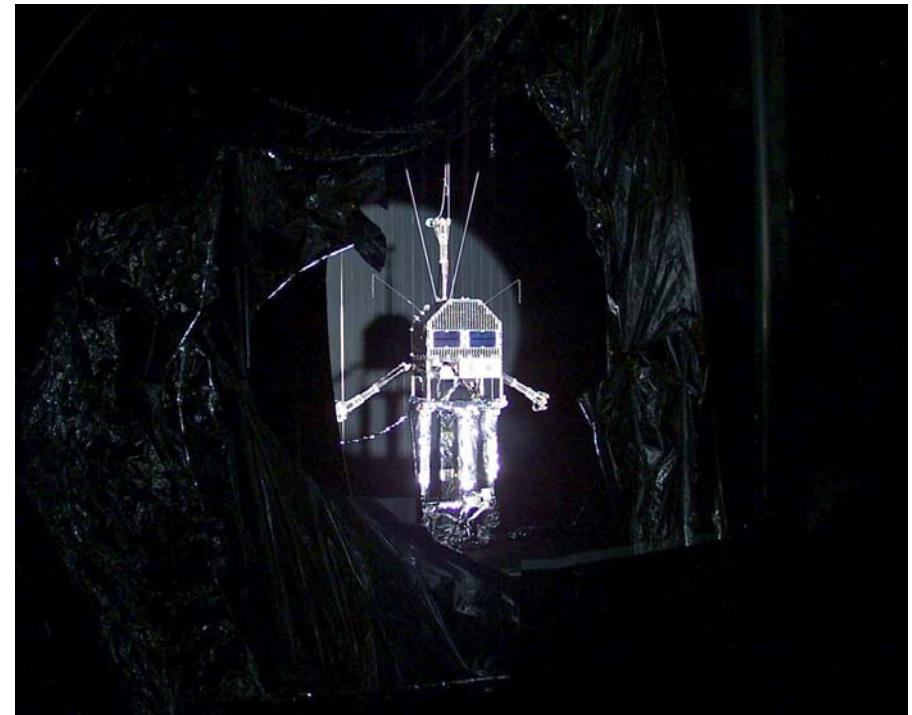
active protective systems :

- heaters (electrical or radioactive)

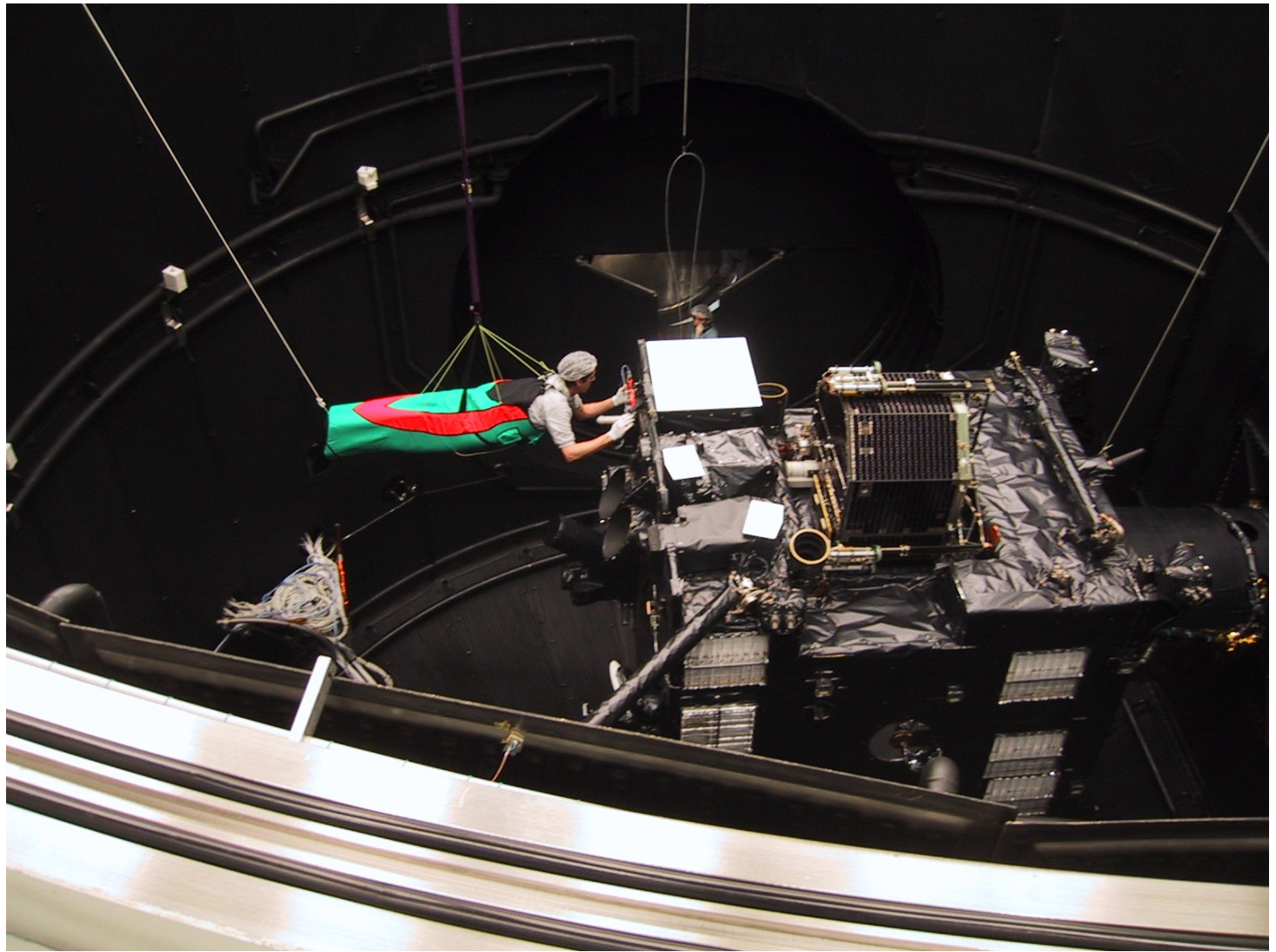
- coolers (Stirling)

- capillary heat pipes (zero-g)

Thermal-Vacuum / Thermal-Balance Test of ROSETTA Lander at IABG, Munich



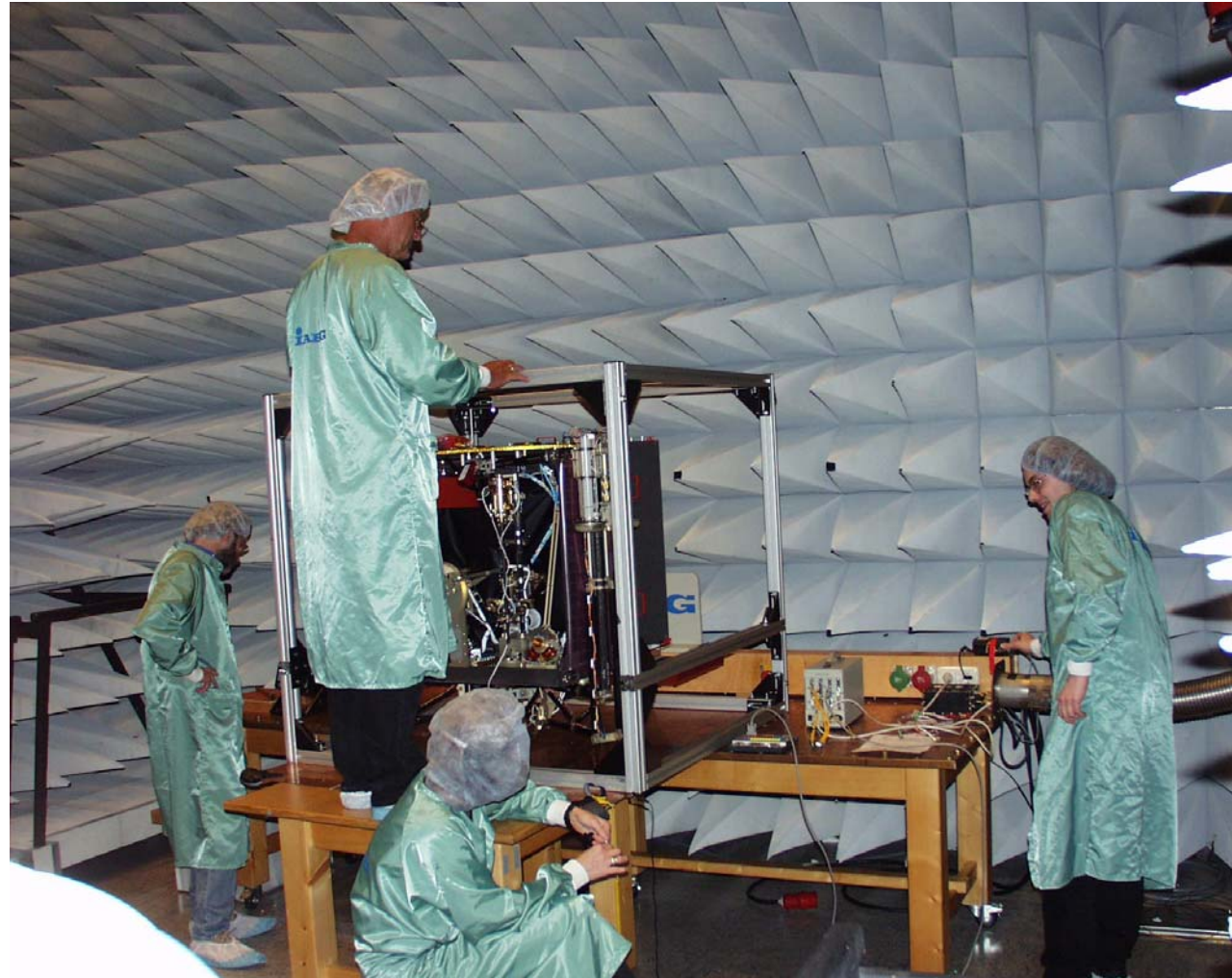
ROSETTA
flight spacecraft
inside Large
Space Simulator
test chamber
at ESTEC, NL



EMC testing of ROSETTA Lander at IABG, Munich:

radiated & conducted
emission,

radiated & conducted
susceptibility



SUMMARY & General Recommendations :

- **Keep track of requirement flowdown !**
- **Assemble (and maintain!) a good technical team !**
- **Start design with resource margins (25% min.) !**
- **Take design reviews serious – they help you !**
- **Nurse back-up solutions along with the main development !**
- **Keep documentation up-to-date !!! - you need it after launch!**
- **Test – test – test !!! (but don't overstress the Flight Unit !)**
- **Hold post-delivery “Lessons Learned“ review with your team !**